

#### **New Product**

# **Dual P-Channel 12-V (D-S) MOSFET**

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	$r_{DS(on)}(\Omega)$	I <sub>D</sub> (A)		
- 12	$0.037 \text{ at V}_{GS} = -4.5 \text{ V}$	- 7.7		
	$0.048 \text{ at V}_{GS} = -2.5 \text{ V}$	- 6.8		
	$0.068 \text{ at V}_{GS} = -1.8 \text{ V}$	- 5.7		

#### **FEATURES**

- TrenchFET<sup>®</sup> Power MOSFETS: 1.8-V Rated
- New Low Thermal Resistance PowerPAK<sup>®</sup> Package



• Ultra-Low r<sub>DS(on)</sub>, and High P<sub>D</sub> Capability



RoHS\*

#### **APPLICATIONS**

- · Load Switch
- PA Switch
- Battery Switch
- Bi-Directional Switch

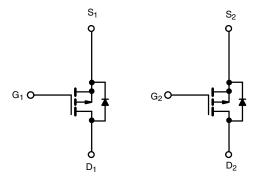
# 3.30 mm 3.30 mm 2 3.30 mm 2 3.30 mm

PowerPAK 1212-8

Bottom View

Ordering Information: Si7909DN-T1

Si7909DN-T1-E3 (Lead (Pb)-free)



P-Channel MOSFET

P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	T <sub>A</sub> = 25 °C,	unless otherwi	se noted		
Parameter		Symbol	10 secs	Steady State	Unit
Drain-Source Voltage		V <sub>DS</sub>	- 12		V
Gate-Source Voltage		V <sub>GS</sub>	± 8		V
Continuous Prain Current /T 150 °C\8	T <sub>A</sub> = 25 °C	- I <sub>D</sub>	- 7.7	- 5.3	
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a</sup>	T <sub>A</sub> = 85 °C		- 5.5	- 3.8	Α
Pulsed Drain Current		I <sub>DM</sub>	- 20		A
Continuous Source Current (Diode Conduction) <sup>a</sup>		I <sub>S</sub>	- 2.3	- 1.1	
Marrian Danier Dissination a	T <sub>A</sub> = 25 °C	P <sub>D</sub>	2.8	1.3	w
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 85 °C	' D	1.5	0.85	VV
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150		°C
Soldering Recommendations <sup>b,c</sup>			2	60	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Manipular to Australia	t ≤ 10 sec	R <sub>thJA</sub>	35	44	
Maximum Junction-to-Ambient <sup>a</sup>	Steady State		75	94	°C/W
Maximum Junction-to-Case	Steady State	R <sub>thJC</sub>	4	5	

#### Notes

a. Surface Mounted on 1" x 1" FR4 Board.

c. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.

b. See Solder Profile (http://www.vishay.com/ppg?73257). The PowerPAK 1212-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.

<sup>\*</sup> Pb containing terminations are not RoHS compliant, exemptions may apply

# Vishay Siliconix

### **New Product**



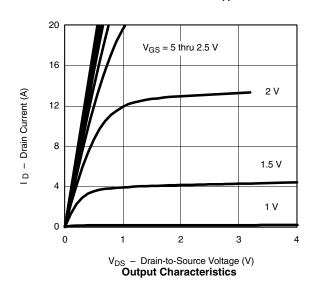
<b>SPECIFICATIONS</b> $T_J = 25$	°C, unles	s otherwise noted					
Parameter	Symbol	Test Condition	Min	Тур	Max	Unit	
Static							
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = -700 \mu A$	- 0.40		- 1.0	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	1	$V_{DS} = -12 \text{ V}, V_{GS} = 0 \text{ V}$			<b>– 1</b>	μΑ	
	IDSS	$V_{DS} = -12 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 85 ^{\circ}\text{C}$			<b>-</b> 5		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 20			Α	
Drain-Source On-State Resistance <sup>a</sup>		$V_{GS} = -4.5 \text{ V}, I_D = -7.7 \text{ A}$		0.031	0.037	Ω	
	r <sub>DS(on)</sub>	$V_{GS} = -2.5 \text{ V}, I_D = -6.8 \text{ A}$		0.040	0.048		
		$V_{GS} = -1.8 \text{ V}, I_D = -3.0 \text{ A}$		0.057	0.068		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	$V_{DS} = -6 \text{ V}, I_{D} = -7.7 \text{ A}$		17		S	
Diode Forward Voltage <sup>a</sup>	$V_{SD}$	$I_S = -2.3 \text{ A}, V_{GS} = 0 \text{ V}$		- 0.7	- 1.2	V	
Dynamic <sup>b</sup>							
Total Gate Charge	$Q_g$			15.5	24		
Gate-Source Charge	$Q_{gs}$	$V_{DS} = -6 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -7.7 \text{ A}$		2.5		nC	
Gate-Drain Charge	$Q_{gd}$			4.3			
Turn-On Delay Time	t <sub>d(on)</sub>			25	40		
Rise Time	t <sub>r</sub>	$V_{DD} = -6 \text{ V}, R_L = 6 \Omega$		45	70		
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D\cong$ – 1 A, $V_{GEN}$ = – 4.5 V, $R_G$ = 6 $\Omega$		90	135	ns	
Fall Time	t <sub>f</sub>			85	130	1	
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	$I_F = -2.3 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}$		70	110		

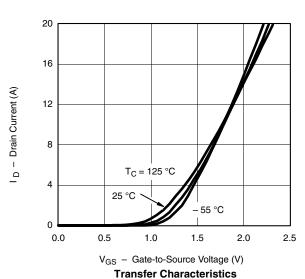
#### Notes

- a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

## **TYPICAL CHARACTERISTICS** $T_A = 25 \, ^{\circ}C$ , unless otherwise noted

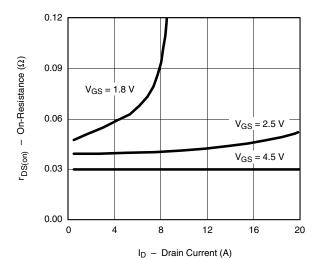




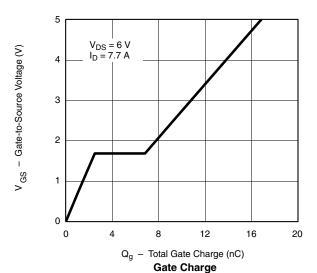


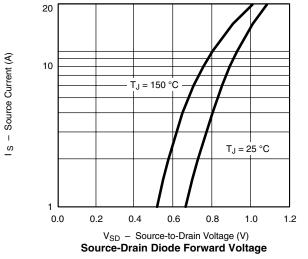
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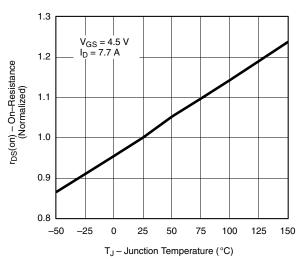
On-Resistance vs. Drain Current



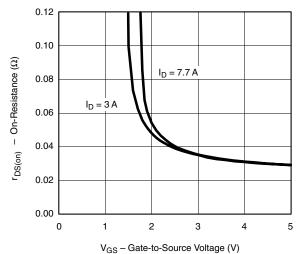


2400 1800 C - Capacitance (pF)  $C_{\text{iss}}$ 1200 Coss 600  $\mathsf{C}_{\mathsf{rss}}$ 0 6 8 0 2 10 12 V<sub>DS</sub> - Drain-to-Source Voltage (V)

Capacitance



On-Resistance vs. Junction Temperature



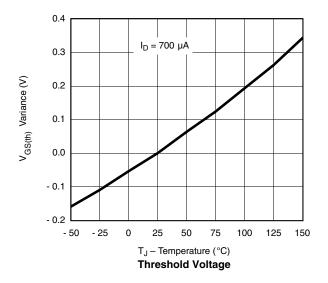
On-Resistance vs. Gate-to-Source Voltage

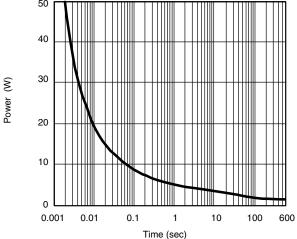
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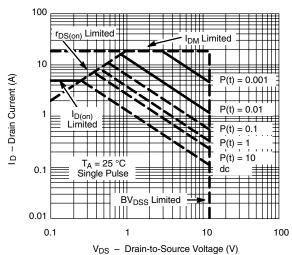


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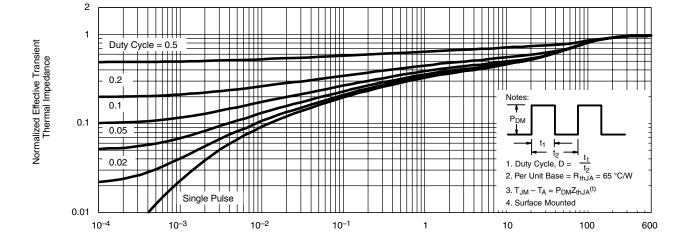




Single Pulse Power, Junction-to-Ambient

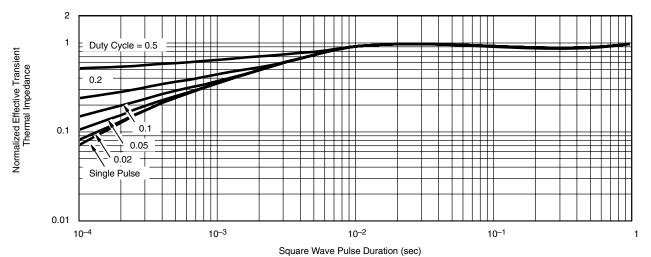


Safe Operating Area, Junction-To-Ambient



Square Wave Pulse Duration (sec)
Normalized Thermal Transient Impedance, Junction-to-Ambient

## **TYPICAL CHARACTERISTICS** $T_A = 25 \, ^{\circ}C$ , unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Case

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## **Legal Disclaimer Notice**



Vishay

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